

# X-Series SMT setup

High Speed Inline AXI platform







With the **X-series platform** Nordson MATRIX presents a dedicated high speed automated X-ray inspection system concept for the inspection of PCB-assembly boards for single/multipanels or samples in trays. All solder joints of SMD and PTH components are covered by a dedicated AXI Algorithm Library.

The Nordson MATRIX system solutions present a modular inspection concept. The platforms feature up to 4 advanced technologies in one system: Transmission X-ray imaging (2D) with patented Slice-Filter-Technique™ (SFT), Off-Axis technology (2.5D) and 3D SART (Simultaneous Algebraic Reconstruction Technique).

The **X-series platform** is available in the following configurations:

- X2 Transmission (2D) + SFT<sup>™</sup>
- X2.5 Transmission (2D) + SFT<sup>™</sup> + Off-Axis (2.5D)
- X3 Transmission (2D) + SFT™ + Off-Axis (2.5D) + 3D SART

## **Features and Benefits**

- High Speed AXI System for In-line and Off-Line setups
- Microfocus X-ray tube (sealed tube / maintenance free)
- Multiple programmable motion system with servo drives
- Digital CMOS flatpanel detector
- Automatic grey-level and geometrical calibration
- Flexible setup for In-line pass through
- Barcode scanner for serial number and product type selection
- Full product traceability via customized MES-Interface

■ PC-Station with multi-core processor setup

**Inspection & Process Software** 

■ Windows 10 platform

## **MIPS Inspection Platform**

- Advanced algorithm library
- CAD import for automatic inspection list generation
- Simultaneous Algebraic Reconstruction Technique (3D SART; X3 only)
- Automatic Tree Classification (ATC) for Auto-Rule-Generation
- Off-line programming for AXI program generation & simulation, tuning and defect reference catalogue

## Verification & process control

- MIPS Verify link with closed loop repair
- MIPS Proces with real time SPC





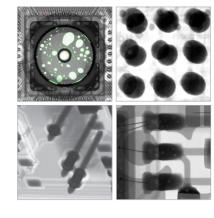
## **Applications**

## Electronic components and solder joint

A unique advanced algorithm library is available for electronic applications, specifically for component and solder-joint inspection on PCB, hybrid or chip level assembly processes.

All standard SMD and THT/PTH components

- BGA & dedicated off-axis head-in-pillow (HIP) algorithm
- Comprehensive QFN & gullwing algorithm
- Robust solder surface / heatsink void inspection
- Pin in paste barel fill measurement
- Discrete down to 1005 pitches



## For more information, speak with your Nordson MATRIX representative.

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## **Specifications**

Facilities		
Dimensions:	1535 mm (H) x 1800 mm (W) x 1575 mm (D)	
Adjustable conveyor height (SMEMA)	950 mm	
Weight:	3.000 kg	
Safe Operating Temperature:	15° - 28 °C optimal 20° - 25° C	
Power Consumption:	max. 6 kW	
Line Voltage:	400 VAC, 50/60 Hz 3 phase, 16 A/	
	208 VAC, 50/60 Hz 3 phase, 25 A	
Air:	5-7 Bar, < 2 l/min, filtered (30µ), dry, oil free	

X-ray Image Chain		
X-ray Source (sealed tube)		
Energy:	SMT-Setup 130 kV/40 W	
Focal Spot Size:	5 microns	
Grey resolution:	14 Bit	
Detector Types:		
CMOS Flatpanel Detector	50 μm pixel size (5 MPix) 75 μm pixel size (3 MPix)	

Motion System	
Multiple axes programmable motion system	
Installed axes	
x,y (linear drives)	sample table
z (servo)	magnification
u,v (linear drives)	detector movement
Conveyor setup	
pass through	single lane

Assembly clearance		
Topside (incl. sample thickness):	35 mm	
Bottom side (excl. sample thickness):	35 mm	
Min. edge clearance for clamping:	3 mm	

Inspection features		
Max. sample size:	460 mm x 360 mm	
Max. inspection area:	460 mm x 360 mm	
Min. sample size	80 mm x 80 mm	
Sample thickness	0,8-10 mm	
Max. sample weight:	5kg	
Angle shot capability:	0 – 40 dgr	
Resolution	down to 5 µm / pix	

Inspection speed	
Transmission (X2, X2.5, X3)	up to 6 views /s
Off-Axis (X2.5, X3)	up to 5 views /s
3D SART (X3)	up to 1 s /FoV

Options
Barcodereader
Low-dose radiation filter